

SPECIFICATION 产品规格书



Contents 目录

1. Description 产品介绍

1.1 General Description 产品描述

1.2 Features 产品特征

1.3 Application 产品应用

1.4 Package Dimension 封装尺寸

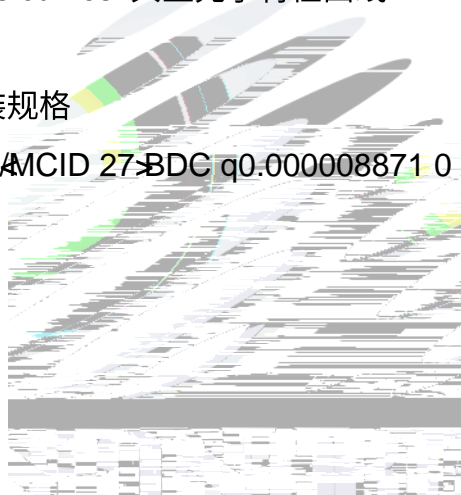
1.5.1 Bin Range Of Forward Voltage and Luminous Intensity (IF=350mA) 电压与光强分 BIN 范围 (IF=350mA)

1.6 Typical optical characteristics curves 典型光学特性曲线

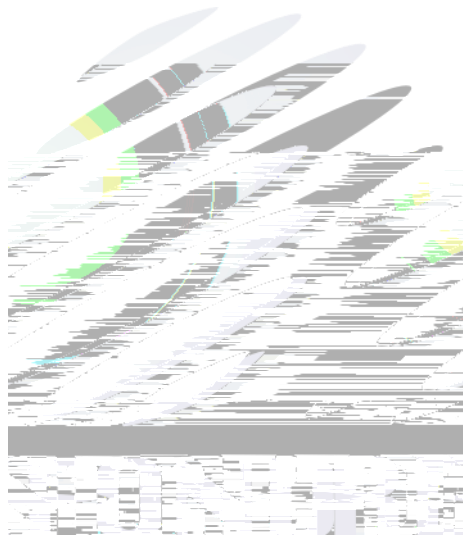
2. Packaging 产品包装

2.1 Packaging Specification 包装规格

2.1.1 TJETQ EMC /Span #MCID 27>BDC q0.000008871 0 595.32 842.04 reW* n351 1* n 0Tm595.3



1. Description 产品介绍



1.4 Package Dimension 封装尺寸

Fig.1-1 Top view 正面视图

Fig.1-2 Side view 侧面视图

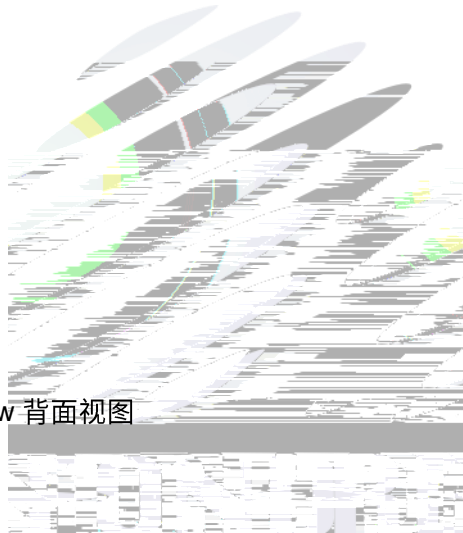


Fig.1-3 Bottom view 背面视图

Fig.1-4 Polarity 极性

Fig.1-5 Soldering 08871 0 595.32 842.04 reW* nBT/F2 10.56 Tf1 0 0 1 133.7 207.62a/60842.04 reW* nB

Table 1-1 Electrical / Optical Characteristics at Ts=25°C 电性与光学特性

Item 项目	Symbol 符号	Test Condition 测试条件	Value			Unit 单位
			Min. (最小值)	Typ (典型值)	Max. (最大值)	
Forward Voltage (正向电压)	V _F	I _F =350mA	2.6	---	3.4	V
Luminous Flux (光通量)	IV	I _F =350mA	20	---	40	lm
Total radiant flux (辐射功率)	e	I _F =350mA	500	---	850	mW
Dominant Wavelength (波长)	D	I _F =350mA	445	---	460	nm
Reverse Current (漏电流)	I _R	V _R =5V	---	---	10	uA
Viewing Angle (发光角度)		I _F =350mA	---	120	---	deg

Table 1-2 Absolute Maximum Ratings at Ts=25°C 绝对最大值

Parameter (参数)	Symbol (符号)	Rating (值)	Units (单位)
Power Dissipation (功耗)	P _D	5100	mW
Forward Current (正向电流)	I _F	1500	mA
Peak Forward Current (峰值电流)	I _{FP}	1650	mA
Reverse Voltage (反向电压)	V _R	5	V
Electrostatic Discharge (HBM) (静电)	E _{SD}	2000	V

Operating Temperature (操作温度)	T_{OPR}	-40 ~ +85	
Storage Temperature (储存温度)	T_{OPR}	-40 ~ +85	
Junction Temperature (结温)	T_J	125	

Notes 备注:

- 1/10 Duty cycle, 0.1ms pulse width. 脉宽0.1ms,占空比1/10.
- The above forward voltage measurement allowance tolerance is $\pm 0.1V$. 以上所示电压测量误差 $\pm 0.1V$.
- The above Dominant Wavelength measurement allowance tolerance is $\pm 1nm$. 主波长测量误差 $\pm 1nm$.
- The above luminous intensity measurement allowance tolerance $\pm 10\%$. 上述发光强度的测试允许公差为 $\pm 10\%$.
- Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product. 使用功率不能超过规定的最大值。
- All measurements were made under the standardized environment of Refond. 所有的测试都是在标准测试平台。
- When the LEDs are in operation the maximum current should be decided after measuring the package temperature junction temperature should not exceed the maximum rate. LED 使用的最大电流需要根据散热条件确定, 结温不能超过最大值。

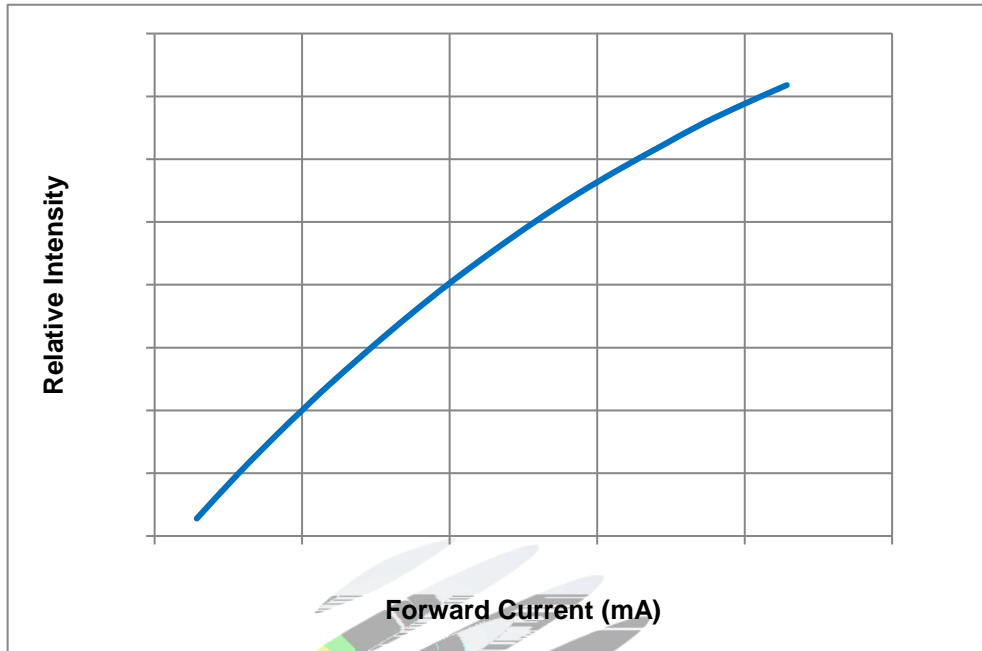


Fig 1-7 Forward Current Vs. Relative Intensity 正向电流与相对光强特性曲线

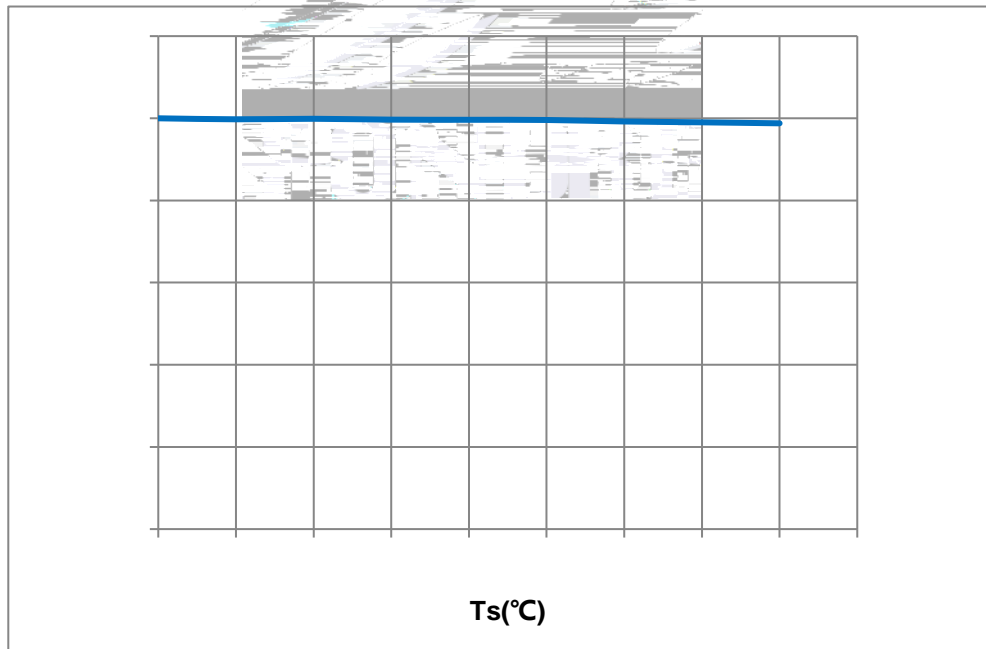


Fig.1-8 Temperature Vs. Relative Intensity 引脚温度与相对光强特性曲线

Fig 1-9 Ts Temperature Vs Forward Current 管脚温度与正向电流特性曲



Fig 1-10 Spectrum Distribution 光谱分布特性曲线

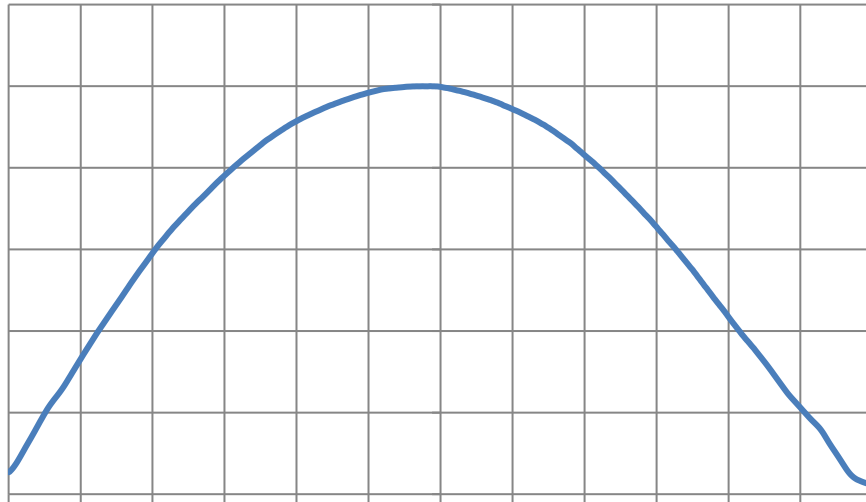
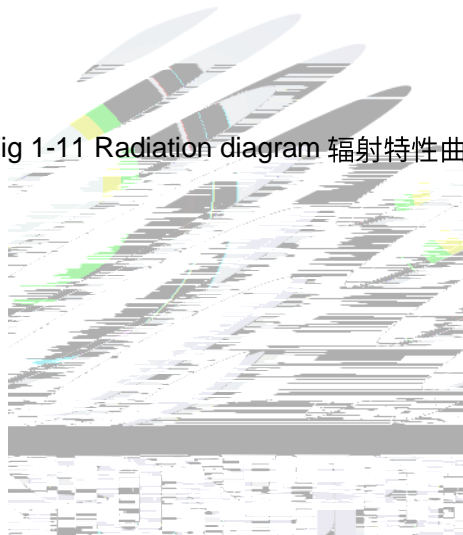


Fig 1-11 Radiation diagram 辐射特性曲线



2. Packaging 产品包装

2.1 Packaging Specification 包装规格

Package: 1000pcs/reel. 包装每卷

2.1.1 Carrier Tape Dimension 载带尺寸

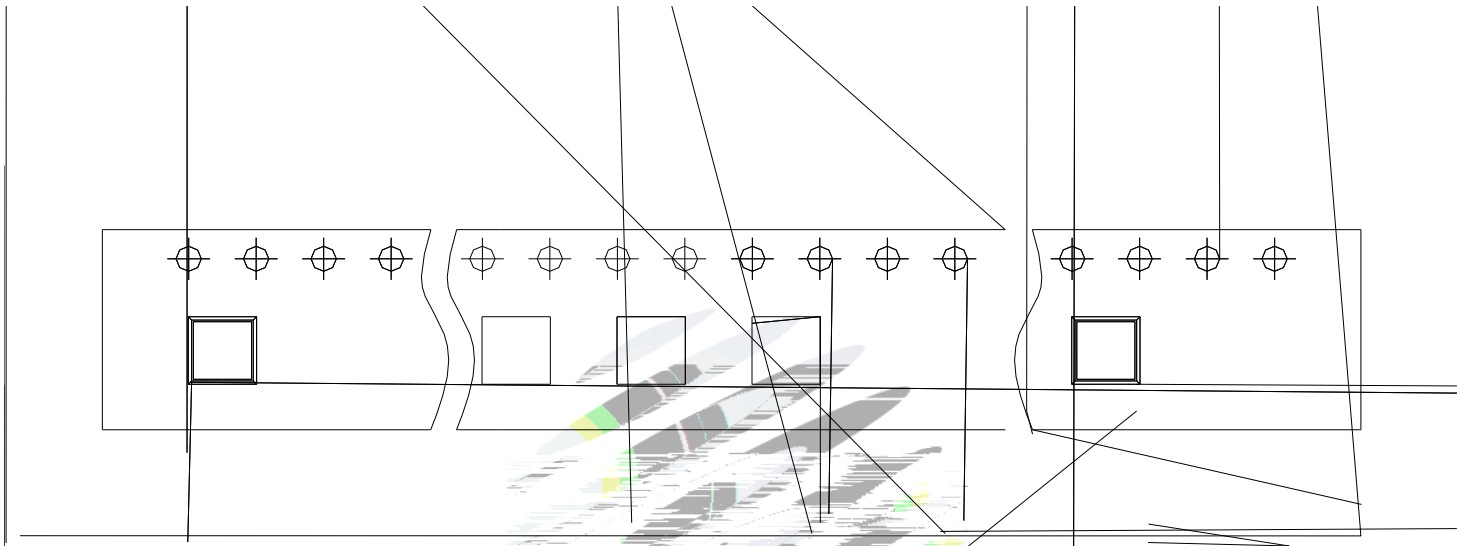


Fig.2-1 Carrier Tape Dimension 载带尺寸

2.1.2 Reel Dimension 卷盘尺寸

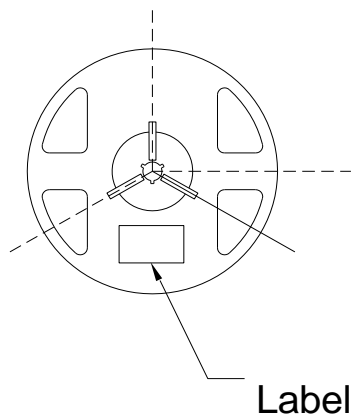


Fig.2-2 Reel 卷盘

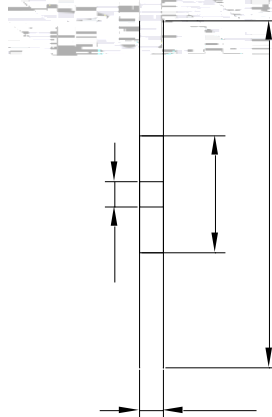


Table 2-1 Reel Dimension 卷盘尺寸

A	14.0±0.5mm
B	178±1mm
C	59±1mm
D	13.9±0.5mm

Notes 备注:

The tolerances unless mentioned ± 0.1 mm. Unit : mm 注: 未注公差为 ± 0.1 毫米, 尺寸单位: 毫米。

2.1.3 Label Form Specification 标签规格

Table 2-2 Label Parameter 标签参数

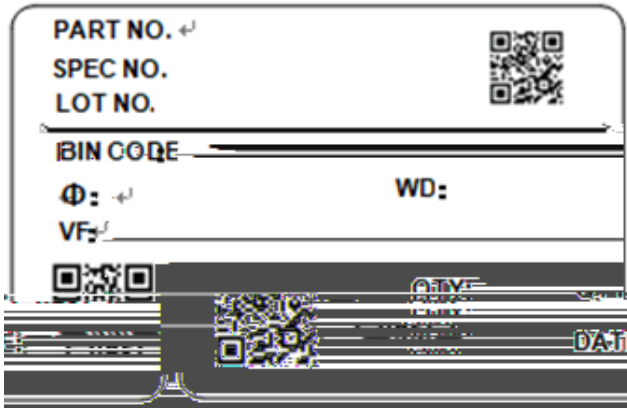


Fig 2-3 Label Form 标签模板

PART NO.	Part Number 品名
SPEC NO.	Spec Number 规格
LOT NO.	Lot Number 批次号
BIN CODE	Bin Code 参数代码
	Luminous flux 光通量
WD	Dominant Wavelength
V _F	Forward Voltage 正向电压
QTY	Packing Quantity 数量
DATE	Made Date 生产日期

2.2 Moisture Resistant Packing 防潮包装

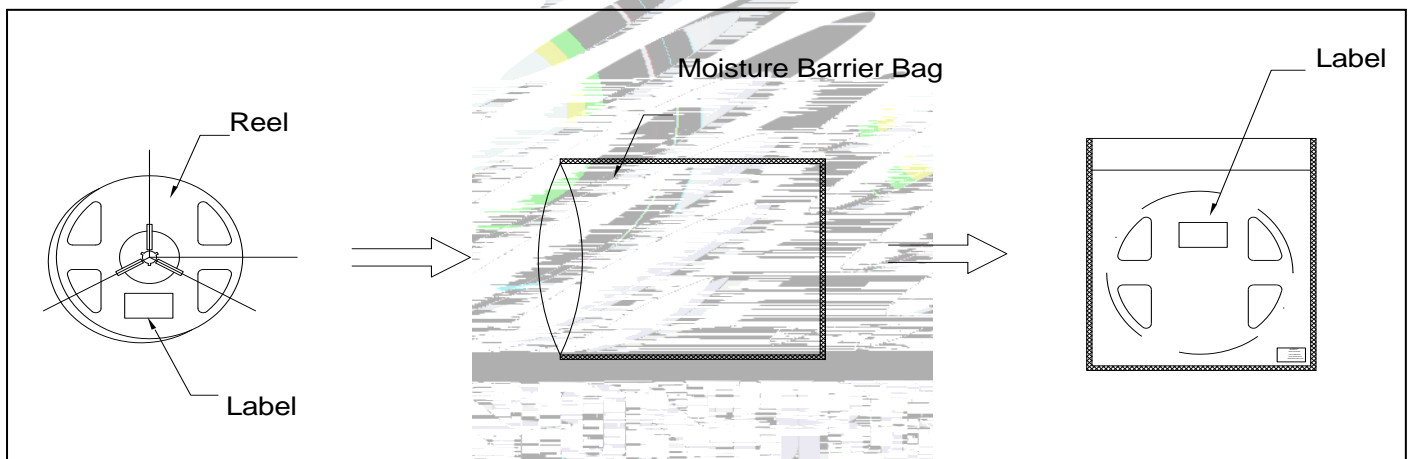


Fig.2- Packing specification 包装说明

2.3 Cardboard Box 包装纸箱

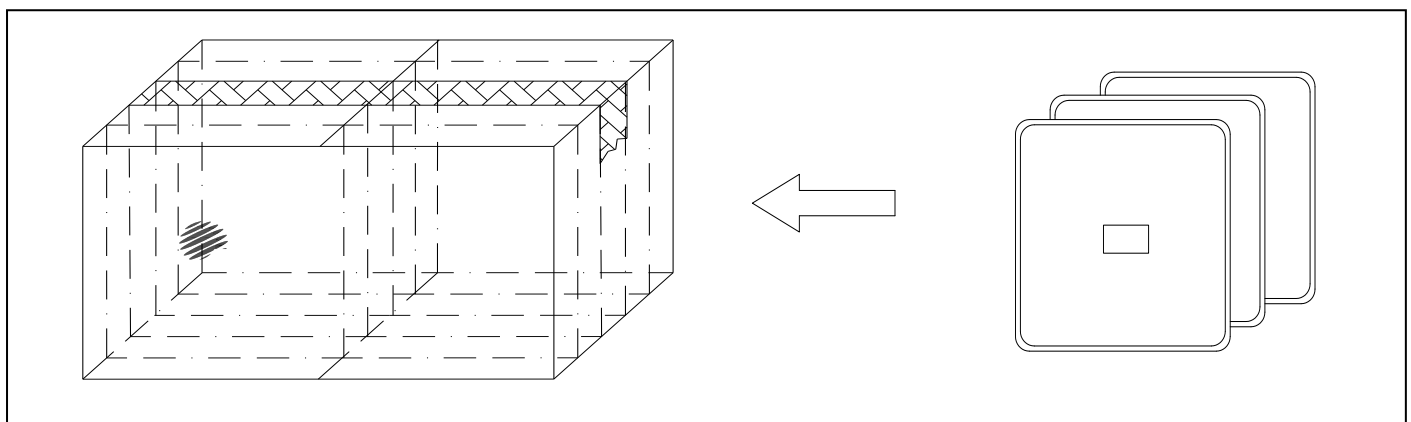


Fig.2- Cardboard Box 包装纸箱

2.4 Reliability Test Items And Conditions 信赖性测试项目及条件

Table 2-3 Test items and conditions 测试项目及条件

Test Items 项目	Ref. Standard 参考标准	Test Condition 测试条件	Time 时间	Quantity 数量	Ac/Re 接收/拒收
Reflow 回流焊	JESD22-B106	T _{emp} : 260°C max T=10 sec	2 times.	10 pcs.	0/1
Thermal Shock 冷热冲击	JEITAED-4701300307	-40°C 15min 10s 100°C 15min	500 cycle.	10 pcs.	0/1
High Temperature Storage 高温保存	JEITAED-4701200201	T _{emp} : 100°C	1000 hrs.	10 pcs.	0/1
Low Temperature Storage 低温保存	JEITA ED-4701200202	T _{emp} : -40°C	1000 hrs.	10 pcs.	0/1
Life Test 常温通电	JESD22-A108	T _A =25°C I _F =350mA	1000 hrs.	10 pcs.	0/1
High Temperature High Humidity Life Test 高温高湿通电	JESD22-A101	60°C / 90%RH I _F =350mA	1000 hrs.	10 pcs.	0/1

ct

回流焊说明

ct

回流焊说明

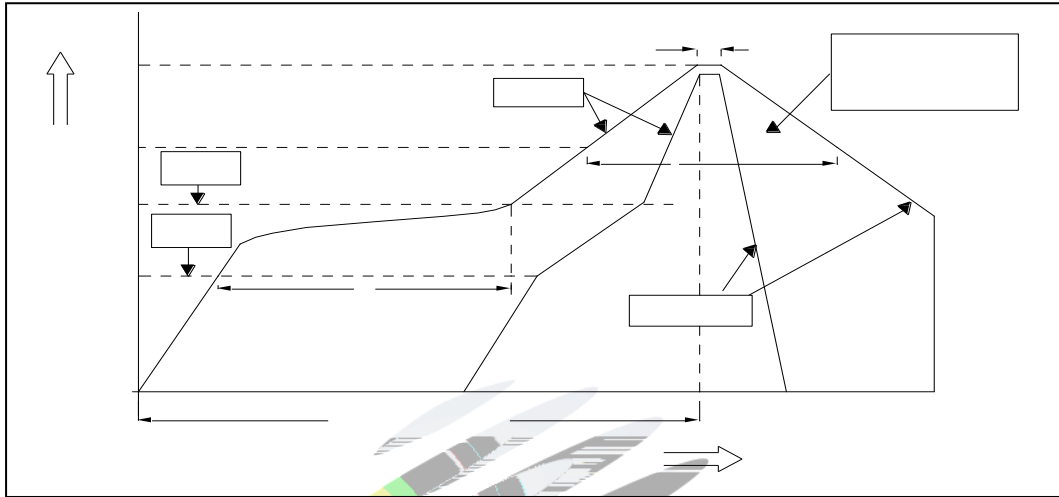


Fig.3-1 SMT Reflow Soldering Instructions SMT 回流焊说明

Table 3-1 SMT Reflow Soldering Parameter SMT 回流焊参数

Average temperature rise speed 平均升温速度 (T _{sm} 至 T _p)	Max 3 °C/ s 最高 3 °C/秒
Preheating: minimum temperature 预热: 最低温度 (T _{sm})	150 °C
Preheating: Max temperature 预热: 最高温度 (T _{sm})	200 °C
Preheating: Time 预热: 时间 (T _{sm} 至 T _{sm})	60 - 120秒 60s-120s
Time limited to maintain high temperature: the temperature 限时维持高温: 温度 (T _L)	217 °C
Time limited to maintain high temperature: The Time 限时维持高温: 时间 (t _L)	Max 60s 最多60秒
Peak /Classification of temperature: 峰值 / 分类温度 (T _p)	260 °C
Time limit classification of peak temperature time 限时峰值分类温度: 时间 (t _p)	Max 10s 最多10秒

Hold time within 5 °C with the actual peak temperature (TP) 与实际峰值温度 (TP) 相差 5 °C 以内的保持时间	Max 30s 最多30秒
Cooling speed 降温速度	Max 6 °C/ s 最高6 °C/秒
Needed time from 25 °C to Tp 25 °C 升至峰值温度所需时间	Max 8 minutes 最多8分钟

Notes 备注:

- (1) The number of reflows should not exceed two, and if the time between reflows exceeds 24 hours, the LED may be damaged due to moisture absorption. 回流焊次数不可以超过两次，两次回流焊的时间间隔如果超过24小时，LED可能由于吸湿而损坏。
- (2) When welding, do not press hard on the surface of the gel while the material is hot. 当焊接时，不要在材料受热时用力压胶体表面。

3.1.1 Soldering Iron 烙铁焊接

- (1) When do soldering by hand, keep the temperature of iron below less 300 less than 3 seconds 当手工焊接时,烙铁的温度必须小于300°C，时间不可超过3秒。
- (2) Soldering by hand should be done only one time. 手工焊接只可焊接一次。

3.1.2 Repairing 修补

Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or not be damaged by repairing.

LED 焊接后再次焊接每次焊接的时间应控制在3秒以内，否则会导致LED本身特性会损坏LED本身的特性。

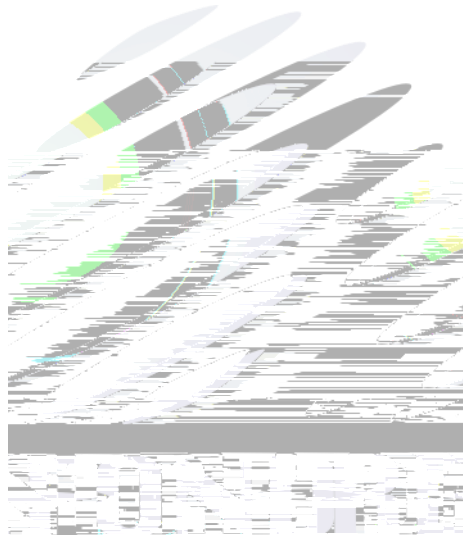
3.1.3 Cautions 注意事项

- (1) The encapsulated material of the LEDs is silicone. Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be impacted on the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when use

the picking up nozzle, the pressure on the silicone resin should be proper. LED封装胶为硅胶，表面光滑，用力按压会导致LED可靠性，因此应有预防措施避免在按压器件。当使用吸嘴时，胶体表面的压力应是恰当的。

(2) Components should not be mounted on warped (non coplanar) portion of PCB. After soldering, do not warp the circuit board. LED灯珠不要焊接在弯曲的PCB板上。焊接完成后，不要弯曲PCB板。

(3) Do not apply mechanical force or excess vibration during the cooling process to normal temperature after soldering. Do not rapidly cool device after soldering.回流焊之后冷却过程中，不要对材料施加外力，也不要震动，回流焊后，不要采用激剧冷却的方式。



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产品使用注意事项

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产品使用注意事项

(1) LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material. This is provided for informational purposes only and is not a warranty or endorsement. LED 工作环境及与 LED 适配的材料中硫元素及化合物成份不可超过 100PPM. 这只是一个建议，不作任何品质担保。

(2) In order to prevent external material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM, the single content of Chlorine element is required to be less than 900PPM, the total content of Bromine element and Chlorine element in the external materials of the application products is required to be less than 1500PPM. This is provided for informational purposes only and is not a warranty or endorsement. 为了防止外界物质进入 LED 内部以造成 LED 的损伤，所处环境及所用套件等等，单一的溴元素含量要求小于 900PPM，单一氯元素含量要求小于 900PPM，溴元素与氯元素总含量必须小于 1500PPM. 这只是一个建议，不作任何品质担保。

(3) VOCs (Volatile organic compounds) emitted from materials used in the construction of fixtures can penetrate silicone encapsulants of LEDs and discolor when exposed to heat and photonic energy. The result can be a significant loss of light output from the fixture. Knowledge of the properties of the materials selected to be used in the construction of fixtures can help prevent these issues. Refond advises against the use of any chemicals or materials that have been found or are suspected to have an adverse affect on device performance or reliability. To verify compatibility, Refond recommends that all chemicals and materials be tested in the specific application and environment for which they are intended to be used. Attaching LEDs, do not use adhesives that outgas organic vapor. 应用套件中的挥发性物质会渗透到 LED 内部，在通电产生光子及热的条件下，会导致 LED 变色，进而造成严重光衰，提前了解套件材料能够避免产生这些问题。瑞丰反对使用任何对 LED

还是仅仅怀疑有害。针对特定的用途和使用环境，瑞丰建议对所有的物质和材料进行相容性的测试。在贴装 LED 时候，不要使用能产生有机挥发性气体的粘结剂。

(4) Handle the component along the side surface by using forceps or appropriate tools; do not directly touch or Handle the silicone lens surface, it may damage the internal circuitry. 通过使用适当的工具从材料侧面夹取，不可直接用手或尖锐金属压胶体表面，它可能会损坏内部电路。

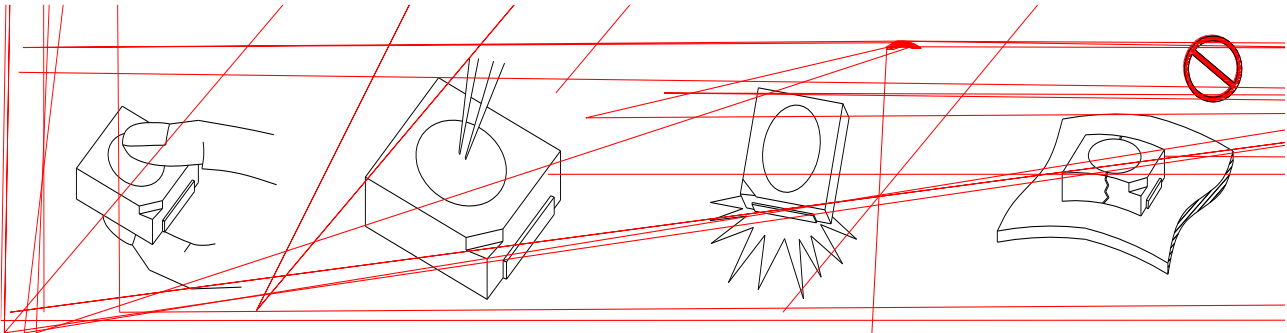


Fig 4-1 Misoperation 错误操作

(5) In designing a circuit, the current through each LED must be exceed the absolute maximum rating specified for each LED. In the meanwhile, resistors for protection should be applied, otherwise slight voltage shift will cause big current change, burn out may happen. The driving circuit must be designed to allow forward voltage only when it is ON or OFF. If the reverse voltage is applied to LED, migration can be generated resulting in LED damage. 设计电路时，通过 LED 的电流不能超过规定的最大值，同时，还需使用保护电阻，否则，微小的电压变化将会引起较大的电流变化，严重时会导致 LED 烧毁。电路设计时必须保证只有在开启或者关闭的时候出现正向电压的变化，不要施加反压，否则会损坏 LED。

(6) Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Color change and so on. Please consider the heat generation of the LEDs when making the system design. LED 容易因为自身的发热和环境的温度改变而改变，温度升高会降低 LED 发光效率，影响发光颜色，所以在设计时应充分考虑散热问题。

(7) Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust requiring special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components. Refond suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause



Declare 申明

This specification is written both in English and in Chinese and the latter is formal.

产品规格书以中英文方式书写，如有冲突以中文版本为准